General Description

SFGMOS® low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially designed to use in synchronous rectification power systems with low driving voltage.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery

Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

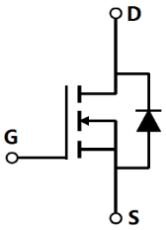
Key Performance Parameters

Parameter	Value	Unit
$V_{DS,\ min}$ @ $T_{j(max)}$	100	V
$I_{D,\ pulse}$	210	A
$R_{DS(ON)\ max}$ @ V_{GS}=10V	10	
Q_g	49.9	nC

Marking Information

Product Name	Package	Marking
SFG10R10IF	TO262	SFG10R10I

Package & Pin information



Absolute Maximum Ratings at T_j=25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	100	V
Gate source voltage	V_{GS}	±20	V
Continuous drain current[1], T_C=25 °C	I_D	70	A
Pulsed drain current[2], T_C=25 °C	$I_{D, pulse}$	210	A
Continuous diode forward current[1], T_C=25 °C	I_S	70	A
Diode pulsed current[2], T_C=25 °C	$I_{S, Pulse}$	210	A
Power dissipation[3], T_C=25 °C	P_D	125	W
Single pulsed avalanche energy[5]	E_{AS}	100	mJ
Operation and storage temperature	T_{stg} T_j	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	1	°C/W
Thermal resistance, junction-ambient[4]	R	62	°C/W

Electrical Characteristics at T_j=25°C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	100			V	V_{GS}=0 V, I_D=250 A
Gate threshold voltage	$V_{GS(th)}$	1.0		2.5	V	V_{DS}=V_{GS}, I_D=250 A
Drain-source on-state resistance	$R_{DS(ON)}$		8.5	10.0		V_{GS}=10 V, I_D=10 A
Drain-source on-state resistance	$R_{DS(ON)}$		9.5	12.0		V_{GS}=4.5 V, I_D=10 A
Gate-source leakage current	I_{GSS}			100	nA	V_{GS}=20 V
				-100		V_{GS}=-20 V
Drain-source leakage current	I_{DSS}			1	A	V_{DS}=100 V, V_{GS}=0 V
Gate resistance	R_G		4.5			

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		2604		pF	V_{GS}=0 V, V_{DS}=50 V, MHz
Output capacitance	C_{oss}		361		pF	
Reverse transfer capacitance	C_{rss}		6.5		pF	
Turn-on delay time	$t_{d(on)}$		20.6		ns	V_{GS}=10 V, V_{DS}=50 V, R_G=2.2 I_D=25 A
Rise time	t_r		5		ns	
Turn-off delay time	$t_{d(off)}$		51.8		ns	
Fall time	t_f		9		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		49.9		nC	V_{GS}=10 V, V_{DS}=50 V, I_D=25 A
Gate-source charge	Q_{gs}		6.5		nC	
Gate-drain charge	Q_{gd}		12.4		nC	
Gate plateau voltage	$V_{plateau}$		3.4		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V_{SD}			1.3	V	I_S=12 A, V_{GS}=0 V
Reverse recovery time	t_{rr}		60.4		ns	V_R=50 V, I_S=12 A,
Reverse recovery charge	Q_{rr}		106.1		nC	
Peak reverse recovery current	I_{rrm}		3		A	

Note

1) Calculated continuous current based on maximum allowable junction temperature.
2) Repetitive rating; pulse width limited by max. junction temperature.
3) Pd is based on max. junction temperature, using junction-case thermal resistance.
4) The value of R is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
5) V_{DD}=50 V,V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

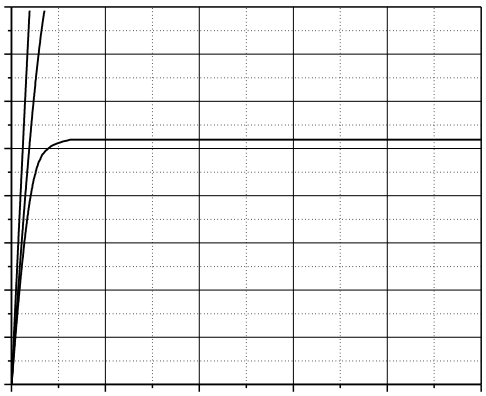


Figure 1. Typ. output characteristics

Figure 2. Typ. transfer characteristics

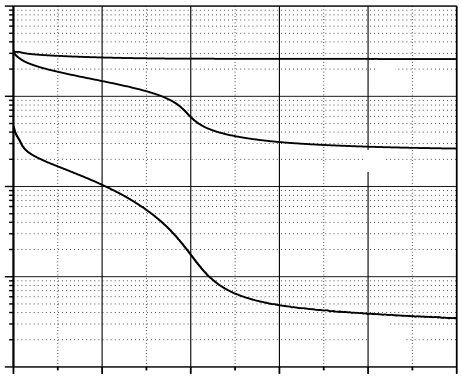


Figure 3. Typ. capacitances

Figure 4. Typ. gate charge

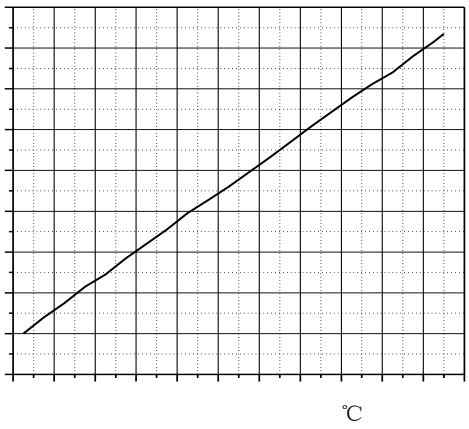


Figure 5. Drain-source breakdown voltage

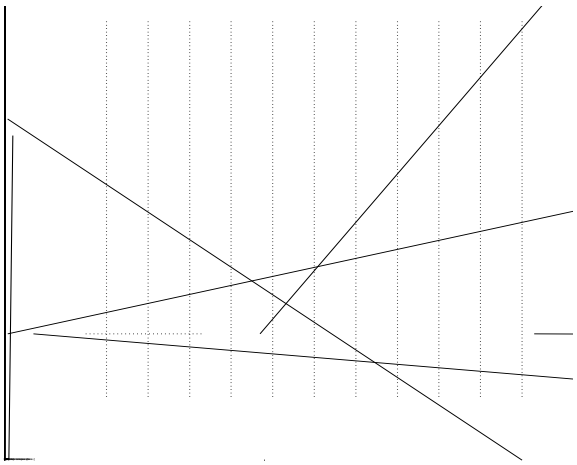


Figure 6. Drain-source on-state resistance

Figure 7. Drain-source on-state resistance

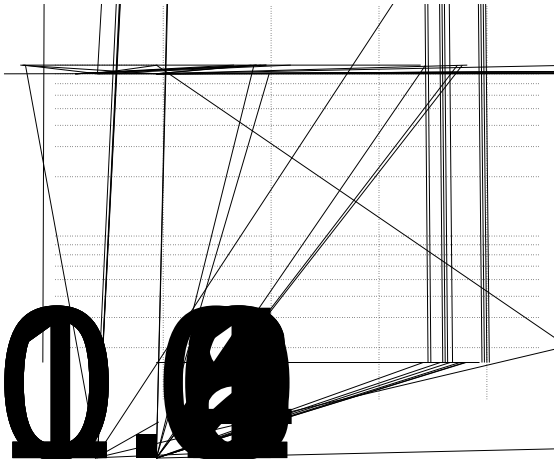


Figure 8. Forward characteristic of body diode

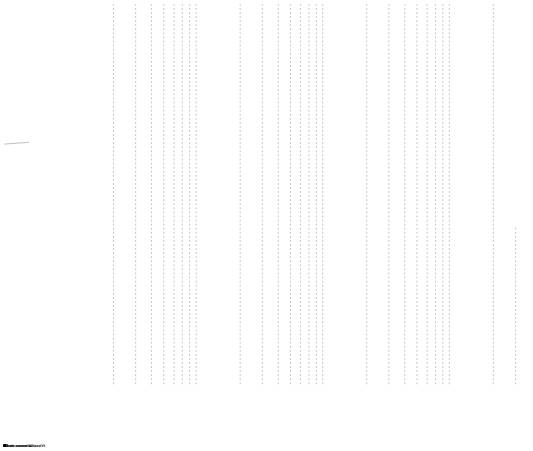


Figure 9. Safe operation area T_C=25 °C

Test circuits and waveforms

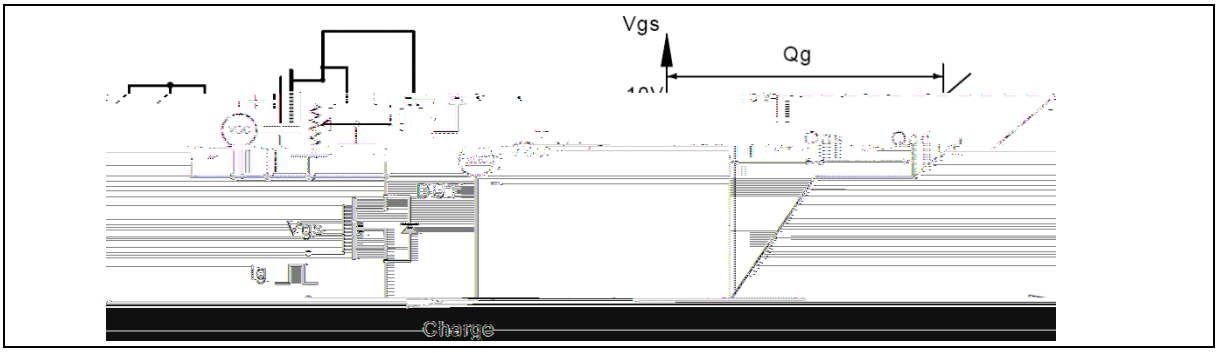


Figure 1. Gate charge test circuit & waveform

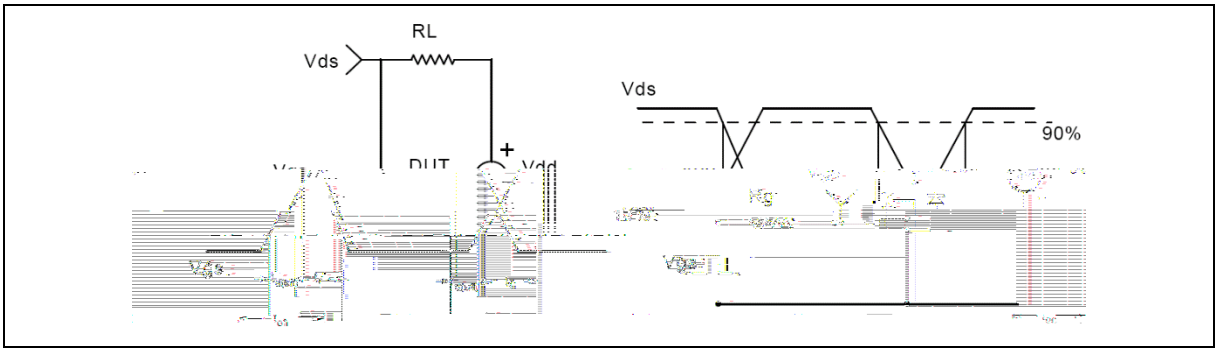


Figure 2. Switching time test circuit & waveforms

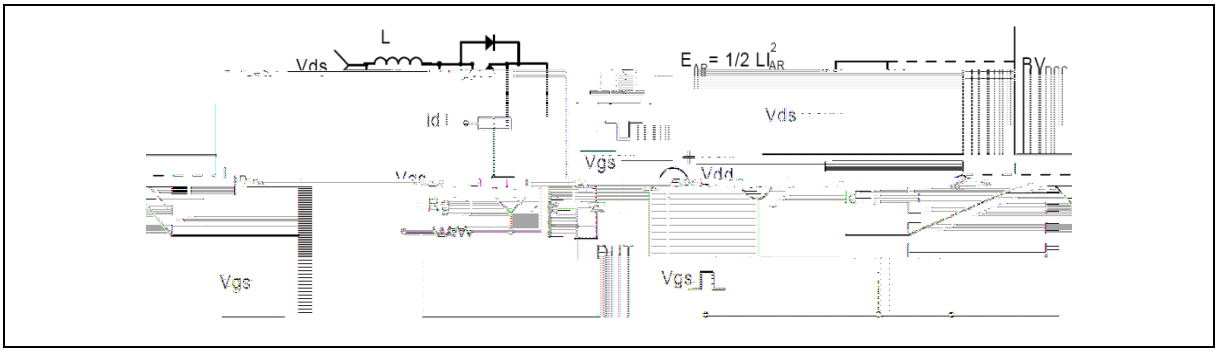


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

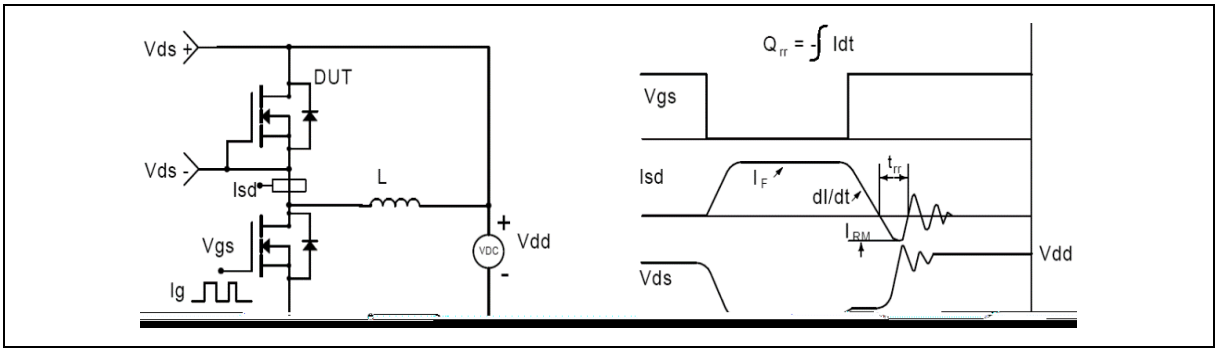
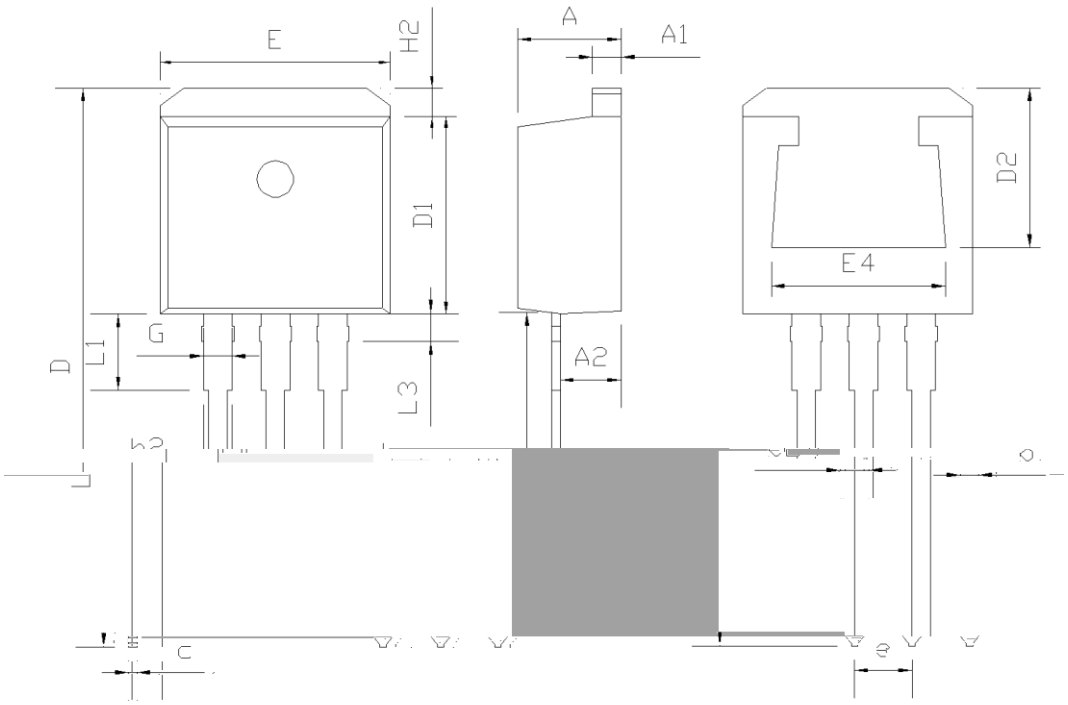


Figure 4. Diode reverse recovery test circuit & waveforms

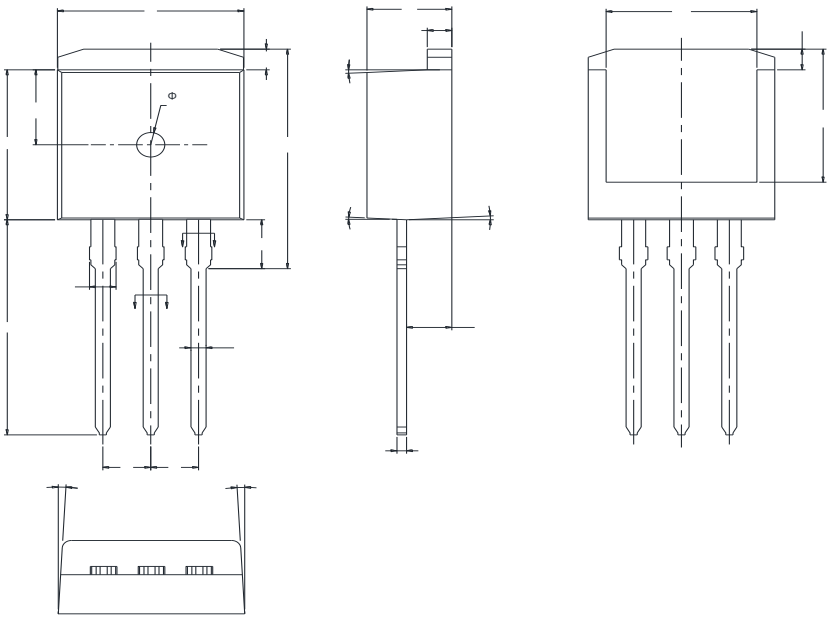
Package Information



Symbol	mm		
	Min	Nom	Max
A	4.34	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
b	0.71	0.81	0.96
b2	1.17	1.27	1.42
c	0.28	0.38	0.53
D	23.20	23.70	24.02
D1	8.50	8.70	8.90
D2	6.00	-	-
E	9.86	10.16	10.36
E4	7.06	-	-
e	2.54 BSC		
H2	-	-	1.50
L	13.33	13.73	14.13
L1	3.50	3.75	4.00
L3	1.28	1.43	1.58
G	1.25	1.35	1.50

Version 1: TO262-C package outline dimension

Package Information



Symbol	mm		
	Min	Nom	Max
A	4.40	4.50	4.60
A1	2.20	2.40	2.60
b	0.76	-	0.89
b1	0.75	0.80	0.85
b2	1.23	-	1.37
b3	1.22	1.27	1.32
c	0.47	-	0.60
c1	0.46	0.51	0.56
c2	1.25	1.30	1.35
D	9.10	9.20	9.30
D1	8.00	-	-
E	9.80	9.90	10.00
E1	7.80	-	-
e	2.54 BSC		
L	12.90	13.20	13.50
L1	2.80	3.00	3.20
L2	1.17	1.27	1.40
L3	4.60 REF		
W	13.25	-	14.00
	1°	3°	5°

Version 2: TO262-J package outline dimension

Ordering Information

Package Type	Units/ Tube	Tubes / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO262-C	50	20	1000	6	6000
TO262-J	50	20	1000	5	5000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFG10R10IF	TO262	yes	yes	yes

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